



Product / Package Information

Package	LFCSP - Sawn
Body Size (mm)	6 X 6 X 0.75 (4.3 EP)
Lead Count	40
Terminal Finish	100 Sn
MS Number	MS010610C

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	4.40E-02	86.91	869100	48.43	484274
Thermosets	Epoxy & Phenol Resin	Proprietary	6.47E-03	12.78	127800	7.12	71212
Other inorganic materials	Carbon black	1333-86-4	1.57E-04	0.31	3100	0.17	1727
Subtotal			5.06 E-02	100.00	1000000	55.72	557213

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	3.28 E-02	97.5	975000	36.13	361293
Copper & its alloys	Iron	7439-89-6	7.91 E-04	2.35	23500	0.87	8708
Copper & its alloys	Zinc	7440-66-6	4.04 E-05	0.12	1200	0.04	445
Copper & its alloys	Phosphorus	7723-14-0	1.01 E-05	0.03	300	0.01	111
Subtotal			3.37 E-02	100.00	1000000	37.06	370557

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	3.37 E-05	100.0	1000000	0.04	371

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	2.15 E-03	100.0	1000000	2.37	23655

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	1.05 E-03	99.0	990000	1.15	11521
Precious metals	Palladium	7440-05-3	1.06 E-05	1.0	10000	0.01	116
Subtotal			1.06 E-03	100.0	1000000	1.16	11638

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	2.86 E-03	100.0	1000000	3.15	31494

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	3.63 E-04	77.00	770000	0.40	3995
Other organic materials	Acrylic resin	Proprietary	3.30 E-05	7.00	70000	0.04	363
Other organic materials	Acrylate	Proprietary	2.59 E-05	5.50	55000	0.03	285
Other organic materials	Polybutadiene derivative	Proprietary	2.12 E-05	4.50	45000	0.02	233
Other organic materials	Epoxy resin	Proprietary	1.18 E-05	2.50	25000	0.01	130
Other organic materials	Butadiene Copolymer	Proprietary	7.07 E-06	1.50	15000	0.01	78
Others	Additive	Proprietary	7.07 E-06	1.50	15000	0.01	78
Others	Peroxide	Proprietary	2.36 E-06	0.50	5000	0.003	26
Subtotal			4.72 E-04	100.0	1000000	0.52	5188

			Weight (g)			Percentage (%)	PPM
Package Totals			9.09 E-02			100	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

